# The Associative Memory system for the FTK processor at ATLAS

Saverio Citraro – University of Pisa & INFN





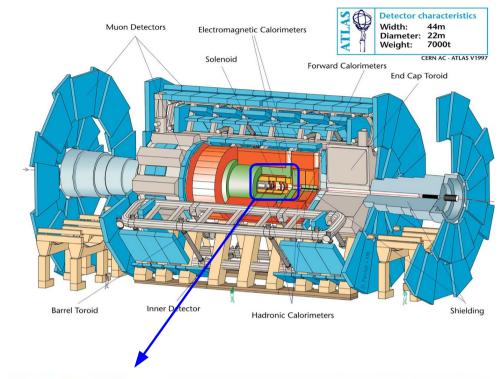
11th International Conference on Large Scale Applications and Radiation Hardness of Semiconductor Detectors
3-5 July 2013, Florence

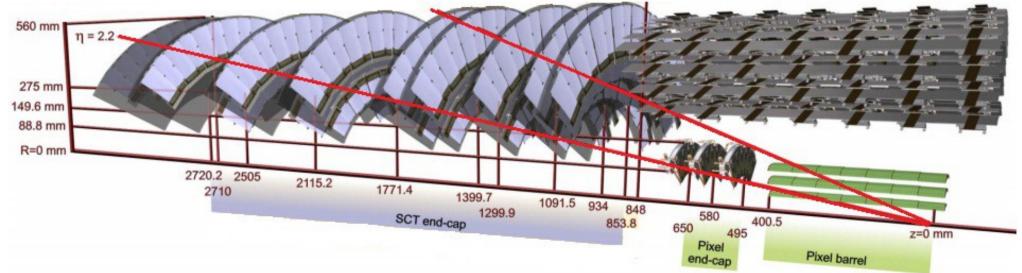
#### **Outline**

- Fast TracKer (FTK): New on-line tracker for Atlas upgrade based on Associative Memory technique
- FTK working principles
- FTK architecture, with a detailed description of the Associative Memory system
- Test of the prototypes (years 2012-2013)
  - Pattern Matching in the AM chip
  - High speed links
  - Crate cooling

# An online silicon detector tracker for the ATLAS upgrade

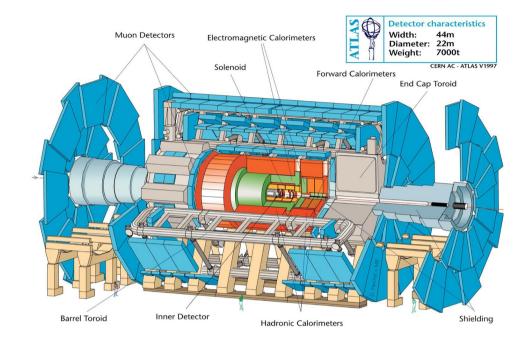
- FTK reconstructs charged particles trajectories in the silicon detector (Pixel & SCT) at "1.5 trigger level".
- Extremely difficult task
  100KHz processing rate
  ~70 overlapping events (pile-up) at highest luminosity.

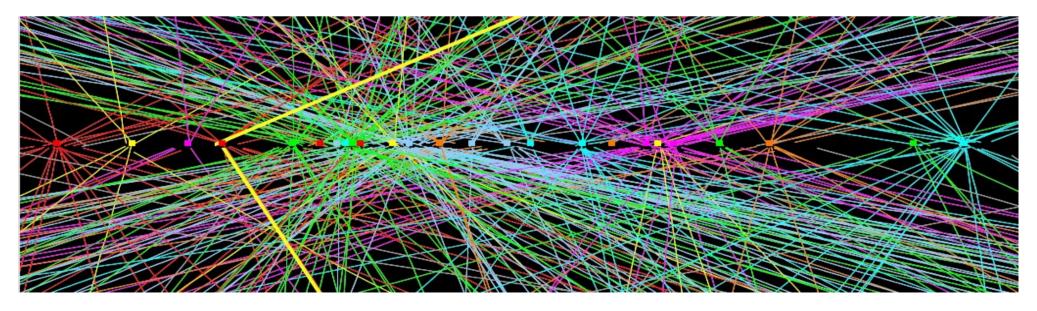




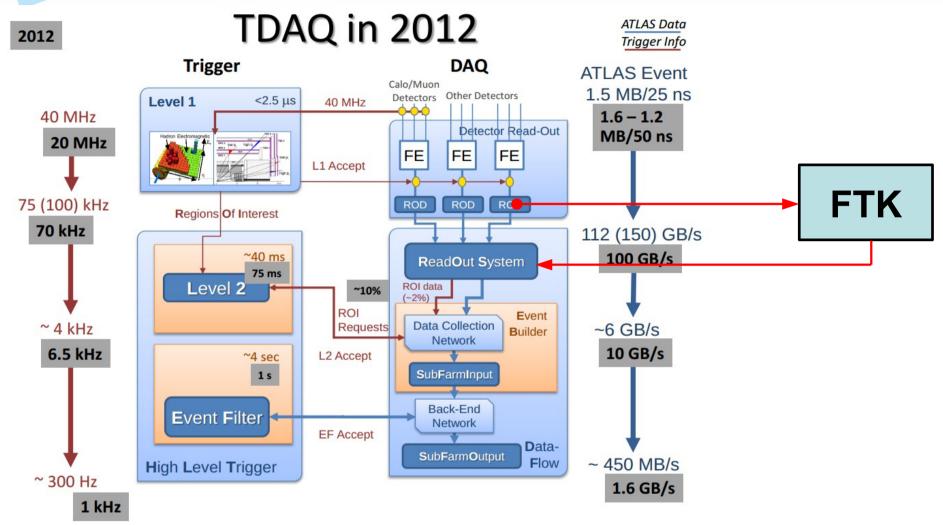
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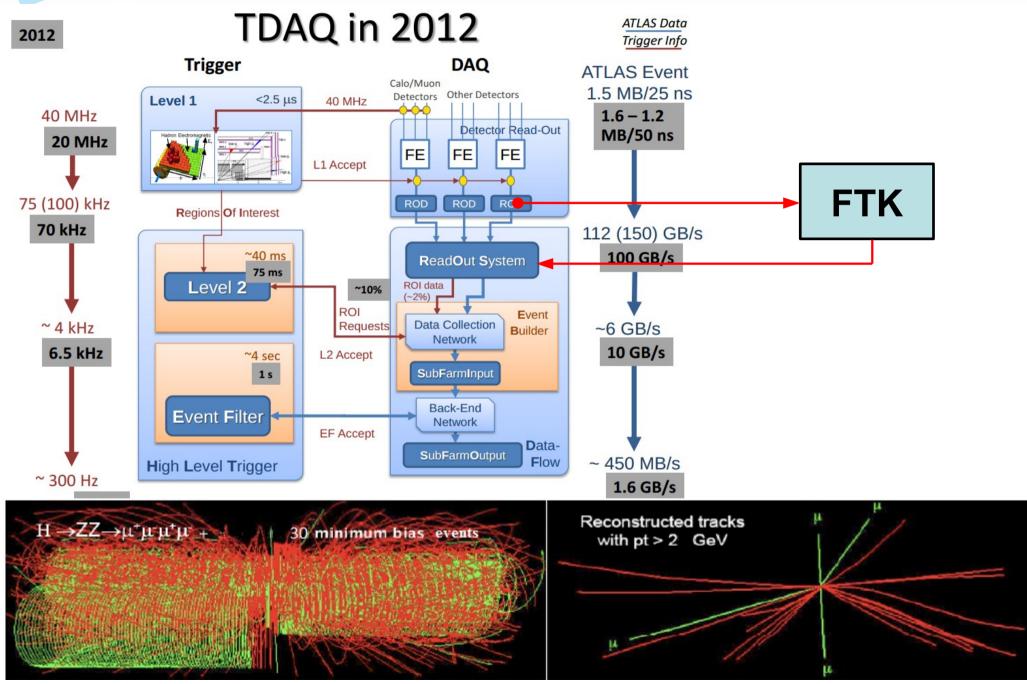


# "1.5 Level Trigger processor"



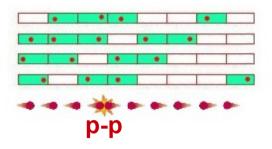
- Silicon data currently used only locally (ROI) and late in Level 2.
- FTK reconstructs all tracks with PT>1 GeV/c in time for Level 2.
- Track parameters are computed with full detector resolution.

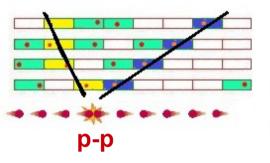
# "1.5 Level Trigger processor"



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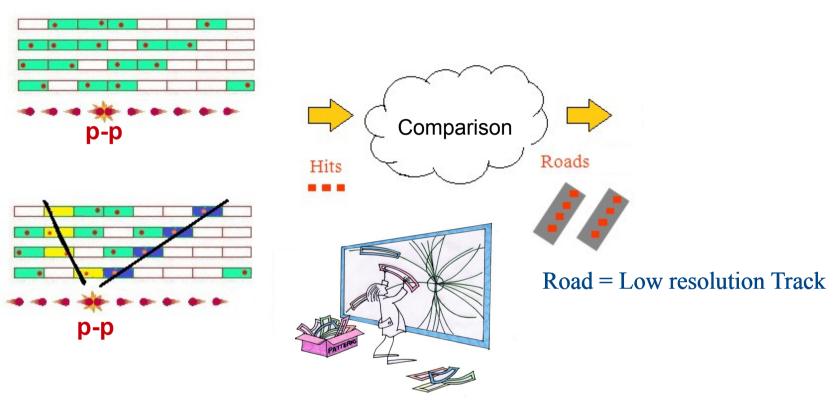
# Pattern matching & track fitting





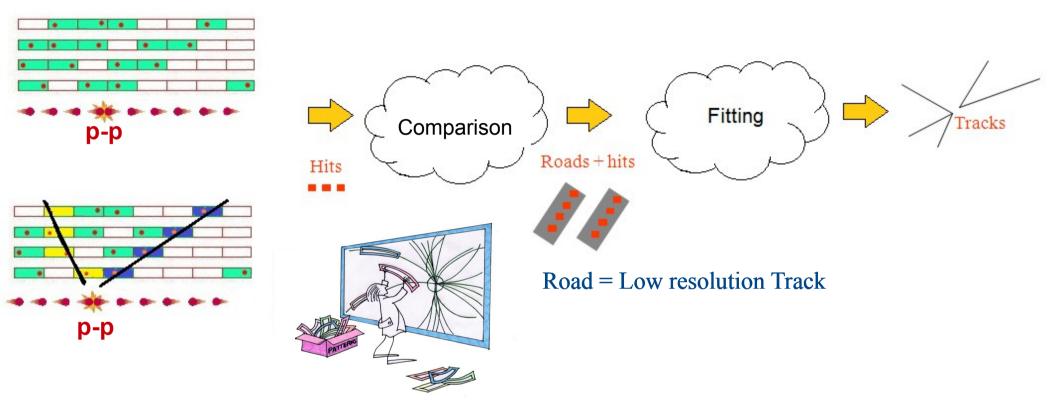
• Pattern Bank: All the possible patterns (low resolution real track candidates) are precalculated and stored in the Pattern Bank.

# Pattern matching



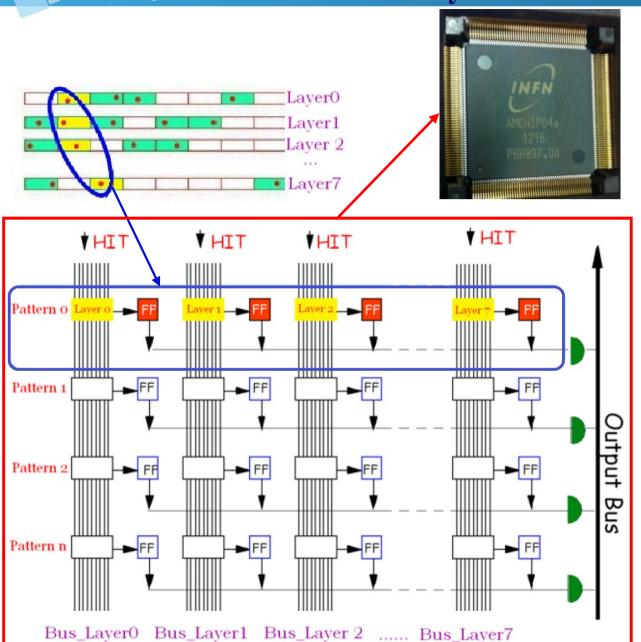
- Pattern Bank: All the possible patterns (low resolution real track candidates) are precalculated and stored in the Pattern Bank.
- Pattern matching: All the hits in each event are compared with all the patterns in the Bank and track candidates (ROADs) are found.

### Pattern matching



- Pattern Bank: All the possible patterns (low resolution real track candidates) are precalculated and stored in the Pattern Bank.
- Pattern matching: All the hits in each event are compared with all the patterns in the Bank and track candidates (ROADs) are found.
- Track Fitting: Fits of the full resolution silicon HITs contained in each ROAD determine particle tracks parameters.

# **Associative Memory**

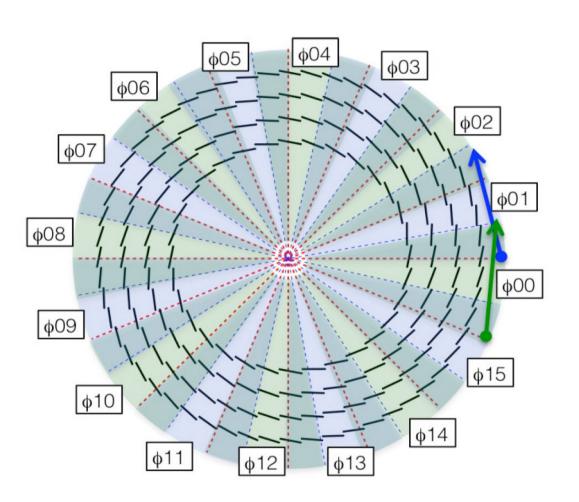


#### **AMchip**

- Custom Associative Memory
- Base element of Pattern Bank
- 1 Pattern stored in 1 row
- Data from 8 silicon layers flow separately on 8 parallel buses (vertical lines)
- Programmable matching threshold
- Matched patterns's addresses are read-out

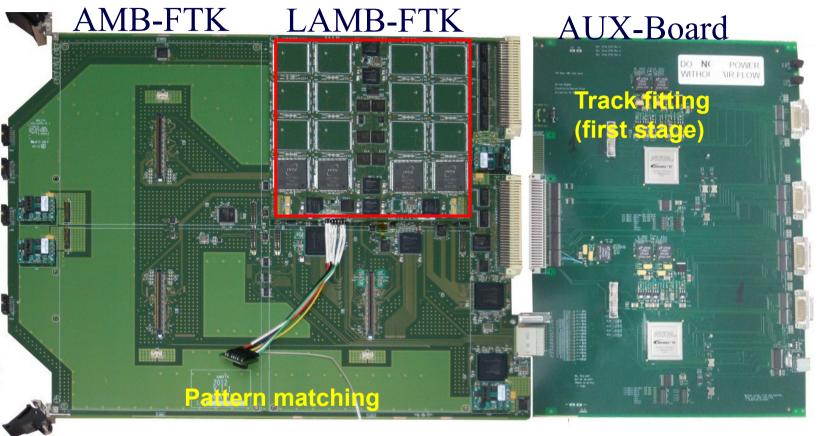
#### FTK architecture CALO MUON TRACKING Clustering Pipeline memories LEVEL 1 TRIGGER **ATCA Data Formatter** RODs LEVEL 2 TRIGGER ROBs **VME** Event builder **AM** AM **EVENT FILTER** Aux AM Aux Aux Board Board Board Board Board Board Data recording • FTK processor: 8 VME Crates 128 PU PU **5 ATCA Crates** • Processing Unit: track **Final Fitting** Final Fitting reconstruction core 32 Boards • 128 Processing Unit: **ATCA** FTK to Level 2 Interface ~1500 FPGAs ~8200 AMChips

# Splitting the silicon detector in 64 η-Φ towers



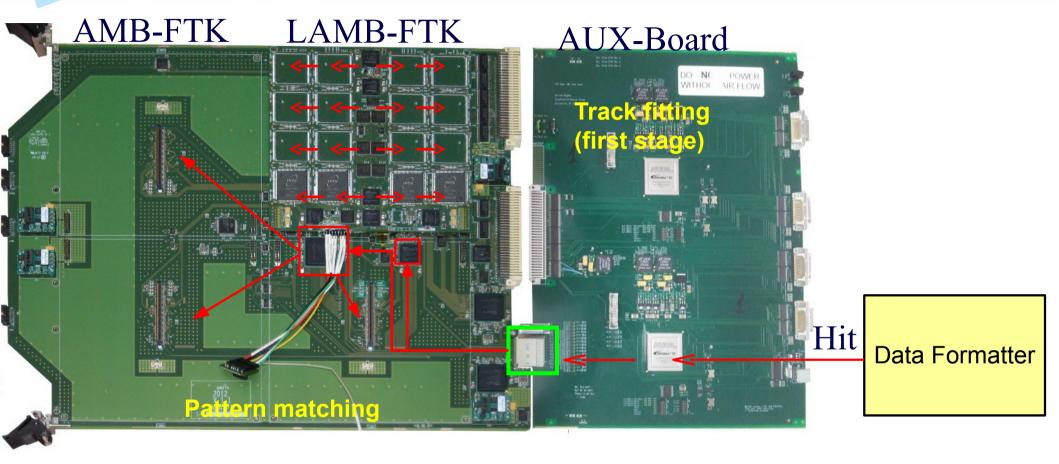
- FTK is organized in 64  $\eta$ - $\Phi$  towers.
- $4 \eta$  sectors times  $16 \Phi$  sectors.
- The blue and green arrows is an example of overlap coverage.

## FTK Processor Unit



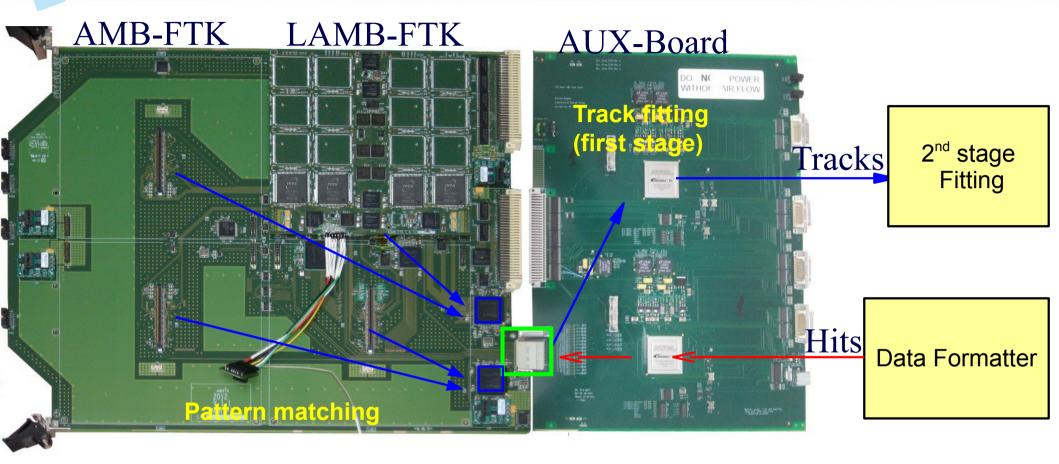
- Processing Unit: 9U VME board (AMB-FTK) + large Rear card (AUX Card)
   + 4 little mezzanines (LAMB-FTK).
- Silicon HITs relative to events accepted by Level 1 (~100kHz) are distributed to all Amchips, this is done in parallel for the 64 tower (1 tower =128 AMChips).
- 1 HIT is compared with  $\sim 8x10^6$  of Precalculated pattern.

#### FTK Processor Unit



- Data are distributed by 12 2Gb/s serial links from Data Formatter to the Input FPGAs on the AMBoard.
- Through 4 LAMB connectors to all 64 AMchips.

#### FTK Processor Unit



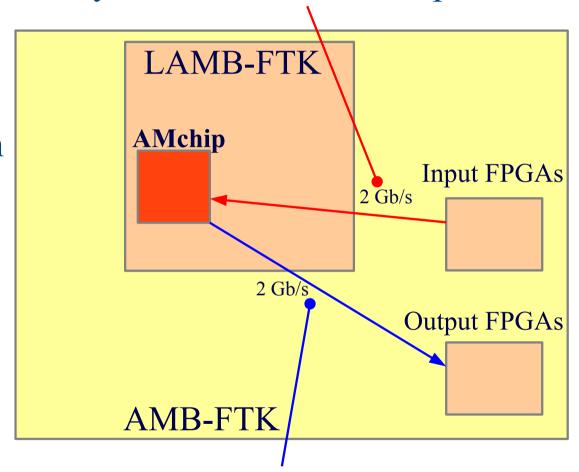
#### Matched ROADs:

- Collected on the AMB-FTK by 2 Output FPGAs (Blue squares).
- Transmitted to the AUX Board through 16 high-speed links (2Gib/s).

### **Prototype Tests**

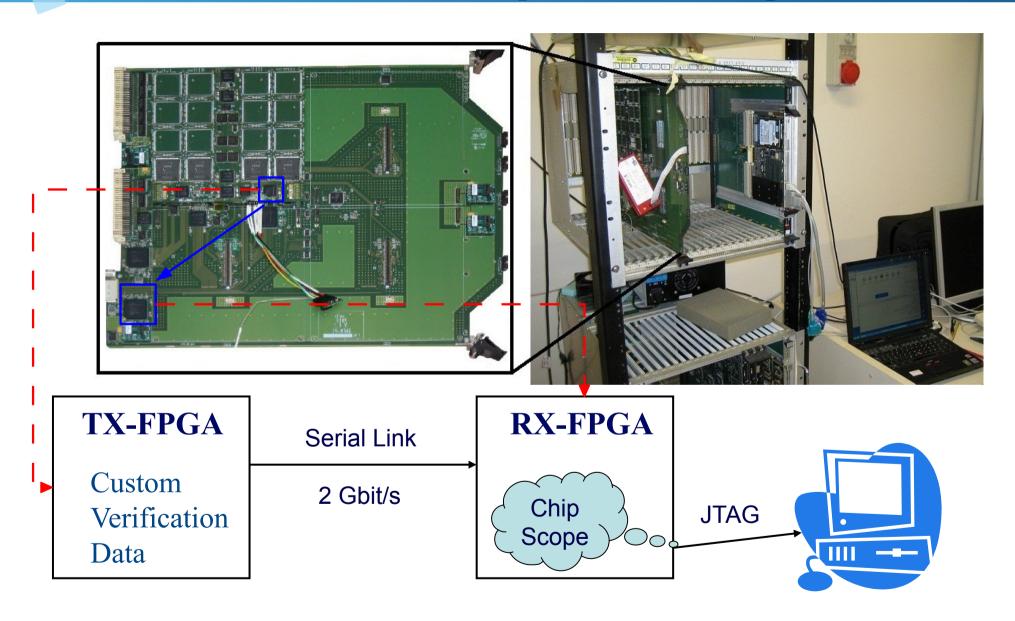
 Test Input Links & FPGAs to correctly send HITs to AM chips.

 Test pattern matching in the AM chips (data versus simulation)



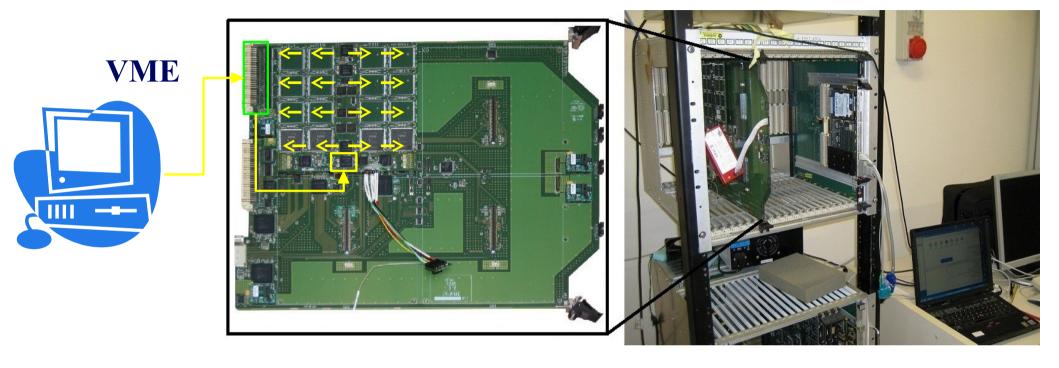
• Test Output Links & FPGAs to correctly collect the ROADs.

# Test direct links: Hit input and Road Output



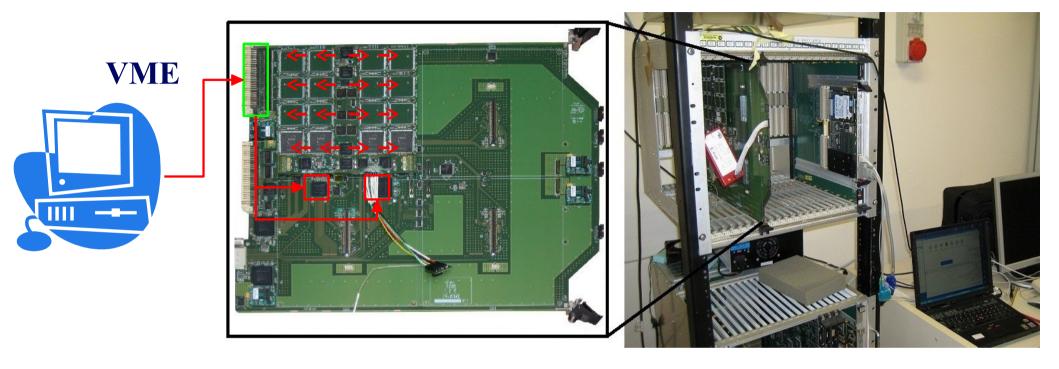
• Sent a known pattern of data from TX and check it in RX with Logical Analyzer.

# Test pattern matching: Store Pattern Bank



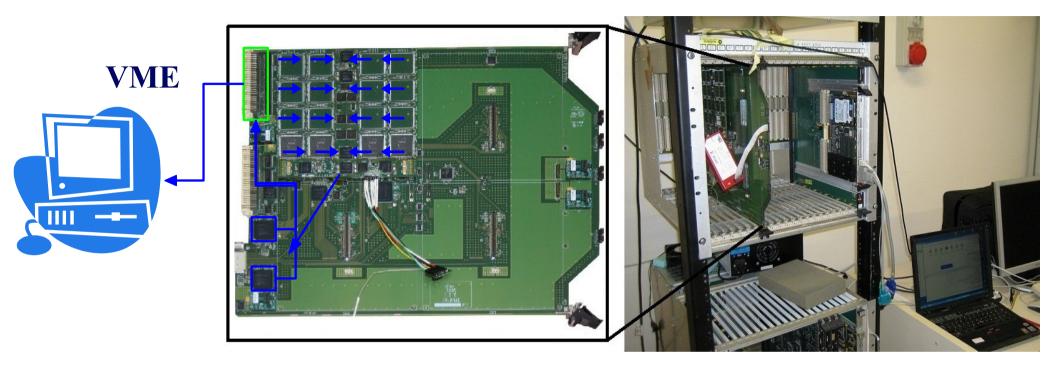
- Step 1: Store precalculated Patterns into Associative memory chips:
  - Through VME the data are stored in the AM by FPGA (yellow arrows)

# Test pattern matching: Send INPUT



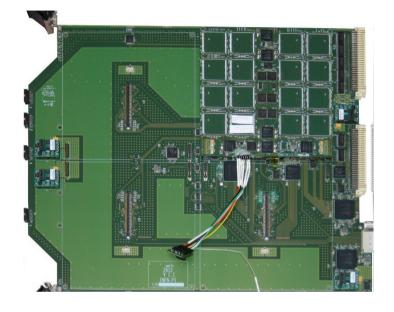
- Step 2: Simulate silicon HITS Input:
  - Silicon HITS Input are loaded into the inputs FPGAs memory (red square) through VME.
  - The FPGAs transimits data to he LAMBs at full speed.

# Test pattern matching: Check OUTPUT



- Step 3: Check pattern matching:
  - Collect ROADs in the Output FPGAs (blue squares)
  - Compare Hardware and Simulation output
- Test Results: Matching done was perfect

## **Cooling Tests**

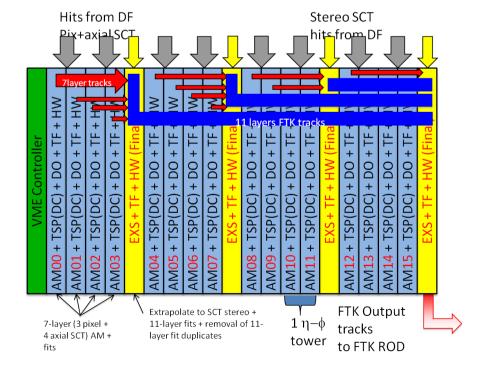


Expected power consumption 1 Processing unit ~ 300 W

16 PU per crate (plus SSB, CPU)

 $\sim$  5 kW per crate.

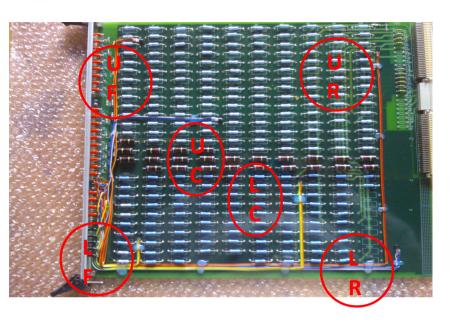
#### Need Cooling test!



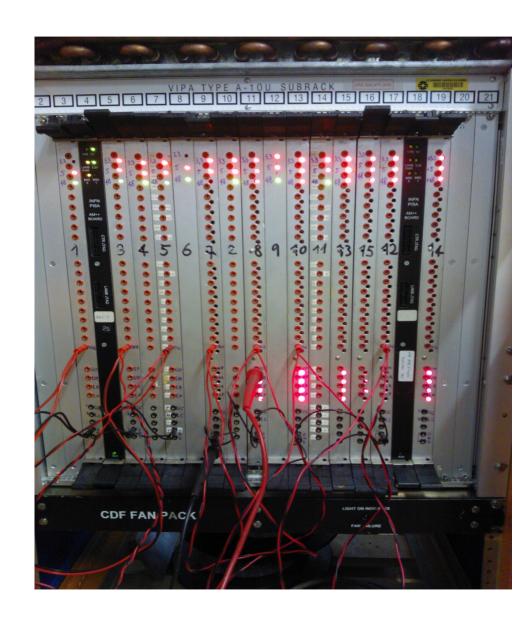
#### Power supply voltages:

- 5V
- 3,3V
- 1,2V

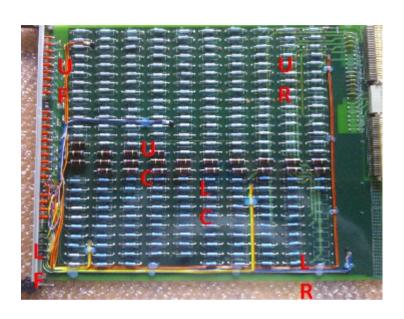
# **Cooling Tests without chiller**



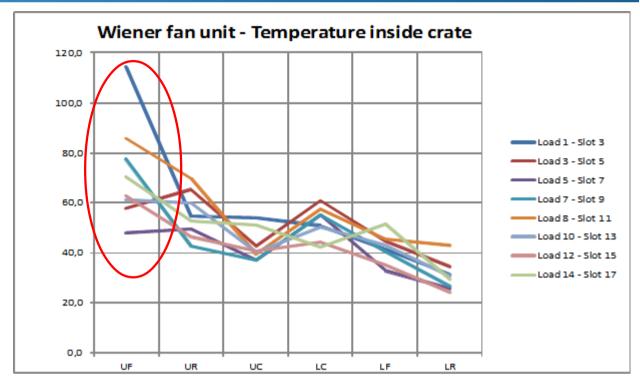
- Cooling test currently in progress INFN PAVIA.
- Power consumption simulated with resistors.
- Six sensor used to measure the temperature in the crate (red circles)



# Cooling Tests Result with Wiener Fan

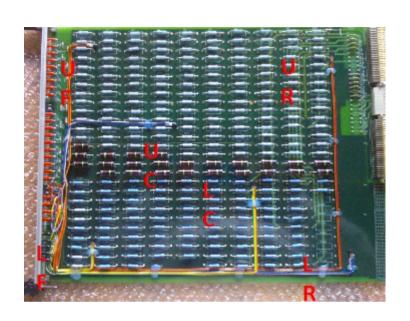


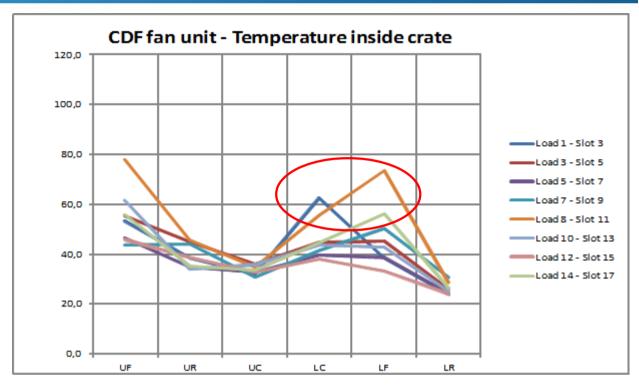




- With the Wiener Fan we have a peak of temperature in the upper side of crate.
- The reason is the power of the fans.

# Cooling Tests Result with CDF Fan







- With CDF Fan the temperature is lower but there is a peak in the down front side of crate.
- The reason is the missing fan.
- Cooling test are in progress: next step is to resolve the problem with fans and use the chiller.

#### Conclusion

- AM system test results were excellent.
- Cooling test are in progress.
- Now we are improving the system for the final version.
- June 21, 013: ATLAS Collaboration approved the FTK Technical Design Report.
- We will install the system for the next LHC power on, in 2015.



